

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-10. (Canceled).

11. (Currently Amended) A process for producing a laminate, comprising the step of thermocompression bonding a core insulating layer, a thermoplastic resin layer, which is disposed on both sides or one side (z-plane) of the core insulating layer, has an adhesive property and has a ~~minimum~~-maximum value of the storage modulus of not more than  $10^6$  Pa at a temperature at or above  $T_g$  of the thermoplastic resin layer, and a metal layer disposed on the surface of the thermoplastic resin layer ~~to one another~~ at a temperature of  $T_g$  or above of the thermoplastic resin layer under temperature conditions such that the storage modulus of the thermoplastic resin is minimum.

12. (Canceled).

13. (Currently Amended) A method for producing an electronic circuit comprising the steps of: providing a laminate comprising a combination of a metal layer with an insulating layer, said laminate having a layer construction of first metal layer/insulating layer/second metal layer or a layer construction of metal layer/insulating layer, the insulating layer having a multilayer structure of two or more layers, the layer on the side of the adhesive interface with the metal layer, out of the layers constituting the insulating layer, being a thermoplastic resin layer, and a maximum value of the storage modulus at a temperature at or above  $T_g$  of the thermoplastic resin layer being not more than  $10^6$  Pa and obtained by thermocompression under temperature conditions such that the storage modulus of the thermoplastic resin is minimum; forming a photosensitive resin layer on a surface of the metal layer of the laminate; and patterning the thus formed photosensitive resin layer to prepare an electronic circuit.

14. (Currently Amended) A method for producing an electronic circuit comprising the steps of: providing an insulating film comprising an insulating layer and a thermoplastic resin layer provided on at least one side of the insulating layer, the thermoplastic resin having a maximum value of the storage modulus of not more than  $10^6$  Pa at a temperature at or above  $T_g$  of the thermoplastic resin layer; laminating the insulating film with a metal layer to prepare a laminate by thermocompression under temperature conditions such that the storage modulus of the thermoplastic resin is minimum; forming a photosensitive resin layer on a surface of the metal layer of the laminate; and patterning the thus formed photosensitive resin layer to prepare an electronic circuit.